

Listing of Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Please cancel claims 1-65 without prejudice or disclaimer.

Please add the following new claim:

66. (New) A semiconductor device comprising:

a semiconductor chip;

first and second radiation members thermally and electrically connected to the semiconductor chip interposed therebetween, and having a radiation surface for radiating heat from the semiconductor chip; and

first and second bonding members respectively interposed between the first radiation member and the semiconductor chip and between the semiconductor chip and the second radiation member, wherein:

the first and second radiation members are made of metallic material that is superior to tungsten and molybdenum in at least one of an electrical conductivity and a thermal conductivity,

wherein the first radiation member is formed by embossing a sufficiently thinned metallic plate to have a protruding portion.